PCN Number:		20170404001		PCN Date:	May 08, 201		17	
	Title: Datasheet for			. Cit Datei	1, 55, 20.		· - 	
		PCN Manager			De	pt:	Quality Services	
	Change Type:	- C., manager				<u> </u>	- Quanty Dervices	
	Assembly Site		Design			Wafe	er Bump Site	
			Data Sheet		一一		Wafer Bump Material	
	Assembly Materials		Part number change				er Bump Process	
	Mechanical Specific		Test Site				er Fab Site	
Packing/Shipping/Labeling			Test Process				er Fab Materials	
<u> </u>						Wafe	er Fab Process	
Notification Details								
	Description of Chang							
	Texas Instruments Inco					otificat	ion.	
	The product datasheet(w.			
	The following change h	istory provides f	urther det	ails.				
	TEXAS						11000440004	
INSTRUMENTS UCD3138064 SLUSB72C -MARCH 2013 -REVISED MARCH 2017								
				5	LUSB/2C	-MARCH 2	2013=REVISED MARCH 2017	
	Changes from Revision B (S	eptember 2014) to Re	vision C				Page	
	Changed Device Groun	ding and Layout Guide	elines section				70	
Changed Device Grounding and Layout Guidelines section								
		e datasheet number will be changing.						
Device Family			Change From:			Change To:		
	UCD3138064		SLUSB72B		SL	SLUSB72C		
These changes may be reviewed at the datasheet links provided.								
	http://www.ti.com/prod			ining provided	۵.			
			_					
	Reason for Change:							
	Reason for Change: To accurately reflect de	vice characterist	ics.					
				uality or Reli	abilit	y (pos	sitive / negative):	
	To accurately reflect de Anticipated impact o	n Fit, Form, Fu	nction, Q					
	To accurately reflect de	n Fit, Form, Fu	nction, Q					
	To accurately reflect de Anticipated impact o No anticipated impact.	n Fit, Form, Fu This is a specific	nction, Q ation char	nge announcen	nent o			
	To accurately reflect de Anticipated impact o No anticipated impact. to the actual device.	n Fit, Form, Fu This is a specific	nction, Q ation char	nge announcen	nent o			
	To accurately reflect de Anticipated impact o No anticipated impact. to the actual device. Changes to product i	n Fit, Form, Fu This is a specific	nction, Q ation char	nge announcen	nent o			
	To accurately reflect de Anticipated impact o No anticipated impact. to the actual device. Changes to product i None.	n Fit, Form, Fu This is a specific	nction, Q ation char esulting f	nge announcen	nent o	only. TI		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com